

**Notice of References Cited**

Application/Control No.

09/408,279

Applicant(s)/Patent Under  
Reexamination  
ROSATO ET AL.

Examiner

Michael Kornakov

Art Unit

1746

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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,313,048	11-2001	Hineman et al.	134/2
	B	US-5,863,344	01-1999	Nam, Jae-woo	134/1.3
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	D. Eisenmann. Prewire Bond Etch. IBM Technical Disclosure Bulletin. No.18, volume 8, page 2590
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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